

SEA & LAND ELECTRONIC CORP.

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ALPHA-TOP TECHNOLOGY CORP.

APPROVAL SHEET

MODEL NO.:	SMD1210-050-16V		
CUSTOMER:			
CUSTOMER'S APPRO	OVAL:		
AUTHORIZED SIGNA	TURE/STAMP:		
DATE		 	

MANUFACTURER:

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Submitted by: Chung Cheng Approved by: YC Lin DATE: 2-Mar-22

SEA & LAND ELECTRONIC CORP.



Features

■ Surface Mount Devices

■ Lead free device

■ Surface Mount packaging

for automated assembly

Applications

Almost anywhere there is a low voltage power supply, up to 30V and a load to be

protected, including:

■ Computer mother board, Modem.

SMD1210-050-16V

Alpha-Top (Sea&Land Alliance)

Performance Specification

Madal	Marking	Mandino	V_{max}	I _{max}	I _{hold}	I_{trip}	P_d		mum Fo Trip	Resis	tance	Agency .	Approval
Model				@25°C	@25°C	Max.	Current	Time	Ri_{\min}	R1max	UL	TUV	
		(Vdc)	(A)	(A)	(A)	(W)	(A)	(Sec)	(Ω)	(Ω)	-		
SMD1210-050-16V	αF	16	100	0.50	1.00	0.60	8.0	0.10	0.180	0.900			

Ihold = Hold Current. Maximum current device will not trip in 25°C still air.

Itrip = Trip Current. Minimum current at which the device will always trip in 25°C still air.

Vmax = Maximum operating voltage device can withstand without damage at rated current (Imax).

Imax = Maximum fault current device can withstand without damage at rated voltage (Vmax).

Pd = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

Rimin/max = Minimum/Maximum device resistance prior to tripping at 25°C.

R1_{max} = Maximum device resistance is measured one hour post reflow.

CAUTION: Operation beyond the specified ratings may result in damage and possible arcing and flame.

Environmental Specifications

Test	Conditions	Resistance change						
Passive aging	+85°C, 1000 hrs.	±5% typical						
Humidity aging	+85°C, 85% R.H., 168 hours	±5% typical						
Thermal shock	+85°C to -40°C, 20 times	±33% typical						
Resistance to solvent	MIL-STD-202,Method 215	No change						
Vibration MIL-STD-202,Method 201 No change								
Ambient operating conditions : - 40 °C to +85 °C								
Maximum surface temperature of the device in the tripped state is 125 °C								

Agency Approvals :

Regulation/Standard:



2015/863/EU

HF

EN14582

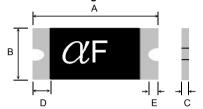
I_{hold} Versus Temperature

inold Tolodo Tollipolate												
Model	Maximum ambient operating temperature (T _{mao}) vs. hold current (I _{hold})											
Model	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C			
SMD1210-050-16V	0.76	0.67	0.58	0.50	0.43	0.40	0.36	0.32	0.28			

Construction And Dimension (Unit:mm)

Model		Α		В		С		E
Model	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.
SMD1210-050-16V	3.00	3.43	2.35	2.80	0.50	1.20	0.30	0.10

Dimensions & Marking



α = TrademarkF = Part identification

Recommended Pad Layout (mm) 1.0 ± 0.1 1.0 ± 0.1 1.0 ± 0.1 1.0 ± 0.1 1.0 ± 0.1 1.0 ± 0.1

Termination Pad Characteristics

Terminal pad materials :

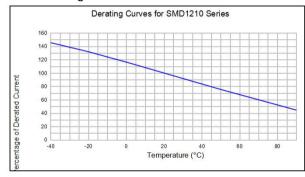
Tin-plated Nickel-Copper

Terminal pad solderability: Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3.

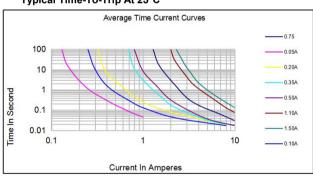
Rework

Use standard industry practices, the removal device must be replaced with a fresh one.

Thermal Derating Curve

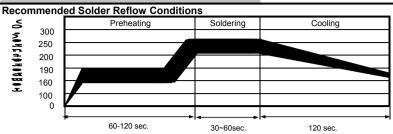


Typical Time-To-Trip At 25°C



NARNING:

- · Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- · Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
 · Use PPTC with a large inductance in circuit will generate a circuit voltage (L di/dt) above the rated voltage of the PPTC.
- Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
- · Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices. PPTC SMD can be cleaned by standard methods.
- · Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profile could negatively impact solderability performance of our devices.



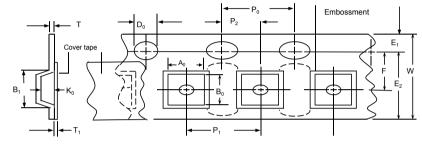
- Recommended reflow methods : IR, vapor phase oven, hot air oven.
- Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25 mm (0.010 inch).
- Devices can be cleaned using standard method and solvents.

Note: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

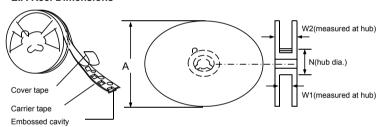
Tape And Reel Specifications (mm)

Governing Specifications	EIA 481-2
W	8.0 ± 0.20
P0	4.0 ± 0.10
P1	4.0 ± 0.10
P2	2.0 ± 0.10
A0	2.82 ± 0.10
B0	3.52± 0.10
B1max.	4.35
D0	1.5 + 0.1, -0.0
F	7.5 ± 0.05
E1	1.75 ± 0.10
E2min.	6.25
Tmax.	0.6
T1max.	0.1
K0	0.90 ± 0.1
Leader min.	390
Trailer min.	160
Reel Dimensions	
A max.	178
N min.	50
W1	8.4 + 1.5, -0.0
W2max.	22.4
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EIA Tape Component Dimensions



EIA Reel Dimensions



Storage And Handling

- Storage conditions : 40°C max, 70% R.H.
- Devices may not meet specified performance if storage conditions are exceeded.

Order Information Packaging

SMD1210	050-16V	Tape & Reel Quantity
Product name	Hold	
Size 3225 mm / 1210 inch	Current	4,000 pcs/reel
SMD: surface mount device	0.50A	

Tape & reel packaging per EIA481-1

Labeling Information

